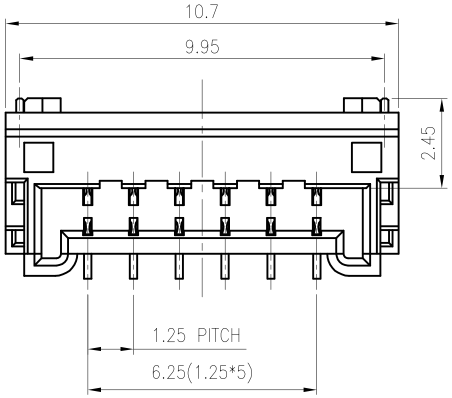
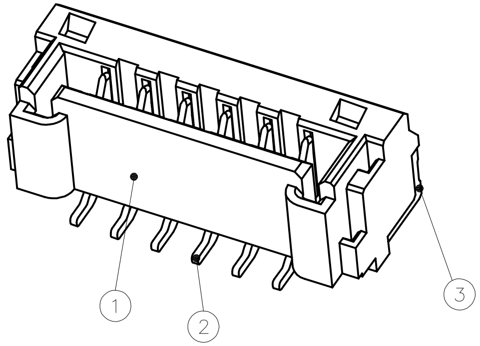
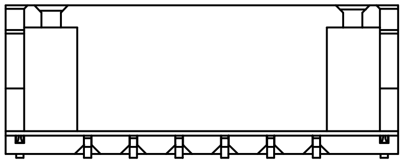
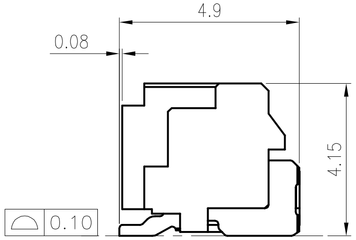


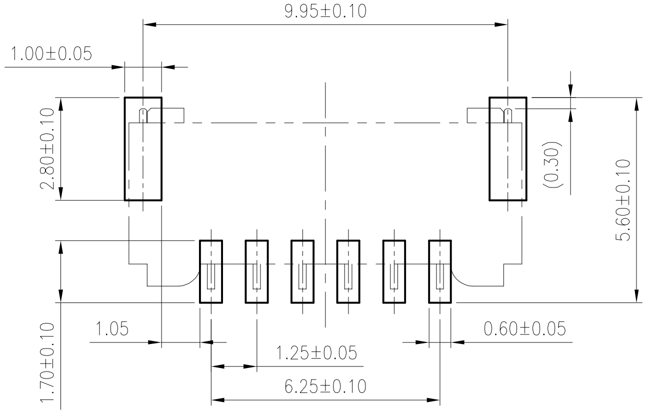


NOTES:
1. MATERIAL:
① HOUSING: THERMOPLASTIC HIGH TEMP.,UL94V-0
② CONTACT: COPPER ALLOY
③ FITTING NAIL: BRASS ALLOY
2. FINISH:
2.1 FITTING NAIL:
50u" MIN. NICKEL UNDERPLATING OVERALL AND
GOLD FLASH PLATING
2.2 CONTACT:
50u" MIN. NICKEL UNDERPLATING OVERALL AND GOLD FLASH PLATING
12u" MIN. GOLD ON CONTACT AREA
3. REFLOW SOLDER CAPABLE TO 260°C
4. AFTER INFRARED REFLOW 260°C 2 CYCLES COPLANARITY 0.10 MAX.
5. PRODUCT SPEC. REFER TO PS-51309-XXXXX-XXX
6. PACKAGE PLS. REFER TO 51309-XXXXX-TRP
7. RoHS COMPLIANT PRODUCTS
8. WITH 51308 MATTING
9. PART NUMBER:

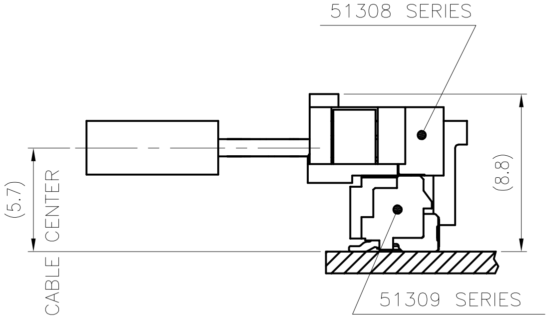
51309-006 X X -001
CKTS
PACKING
0: TAPE & REEL
PLATING:
V: 12u" MIN. GOLD ON CONTACT AREA







RECOMMAND OF PCB LAYOUT



MATED CONDITION

一般公差 TOLERANCES X. ±0.5 .XX ±0.15 .X ±0.25 .XXX ±0.1 ANGLES ±2°	宏致電子股份有限公司 Aces Electronics Co.,Ltd.					
檢驗尺寸標示 SYMBOLS ◈ ◈ INDICATE CLASSIFICATION DIMENSION	品名 (TITLE) 1.25mm IDC MALE SMT S/R R/A TYPE			製圖 (DR) 16'/04/25	MARK	
				審核 (CHKD)	RYAN	
◈ MARK IS CRITICAL DIM. ◈ MARK IS MAJOR DIM.	圖號 (DWG NO.) 51309-XXXXX-XXX			核准 (APPD)	HISATOMI	
表面處理 (FINISH)	比例 (SCALE) 5:1	單位 (UNITS) mm	⊕ ⊏⊐	張數 (SHEET) 1 OF 1	SIZE A4	REV A